

Product Change Notice (PCN)

Subject: Transfer of the wafer production site, and Transfer of the Final Test, Visual Inspection, and Packing site for the RZ/A1M, RZ/A1LU, and RZ/A1LC groups

Publication Date: 6/29/2026

Effective Date: 1/1/2027

Revision Description:

Initial Release

Description of Change:

The wafer production site for the target products will be transferred to Taiwan Semiconductor Manufacturing Co., Ltd. (TSMC). In addition, the Final test, Visual inspection, and Packing sites for the target products will be transferred from Yonezawa factory to Tera Probe, Inc.

Process	Factory Before Change	Factory After Change
Wafer production site	Naka	TSMC
Final Test, Visual Inspection, and Packing site	Yonezawa	Tera Probe

Depending on stock levels and the timing of production switching, there may be cases where either Wafer production at Naka with Final test, Visual inspection, and Packing at Tera Probe, Or Wafer production at TSMC with Final test, Visual inspection, and Packing at Yonezawa.

Naka : Renesas Semiconductor Manufacturing Co., Ltd. Naka Factory

TSMC : Taiwan Semiconductor Manufacturing Co. Ltd

Yonezawa : Renesas Electronics Corporation Yonezawa Factory

Tera Probe : Tera Probe, Inc.

Affected Product List:

R7S721010VCBG#AC0
R7S721011VCBG#AC0
R7S721011VLBG#AC0
R7S721030VCBG#AC0
R7S721031VCBG#AC0
R7S721031VLBG#AC0
R7S721034VCBG#AC0

Reason for Change:

To ensure stable supply and enhance competitiveness, Renesas is pursuing productivity improvements through process standardization, automation and specialization. As part of this initiative, for RZ/A1M, RZ/A1LU, and RZ/A1LC MCU product groups, the wafer production site will be transferred to TSMC, and the final test, visual inspection, and packing site will be transferred to Tera Probe.

Impact on Fit, Form, Function, Quality & Reliability:

No impact on fit, form, function, quality, or reliability.

Product Identification:

Each product can be identified by T/C (Trace Code).

Qualification Status : Now Available

Sample Availability Date : 7/15/2026

PCN samples for the wafer production site will be final-tested at Yonezawa.

Device Material Declaration : Please contact Renesas sales representatives.

Note:

1. Acknowledgement must be received by Renesas within 30 days or Renesas will consider the change as approved.
2. If timely acknowledgement is provided by Customer, then Customer shall have 90 days from the date of receipt of this PCN to make any objections to this PCN. If Customer fails to make objections to this PCN within 90 days of the receipt of the PCN then Renesas will consider the PCN changes as approved.
3. If customer cannot accept the PCN then customer must provide Renesas with a last time buy demand and purchase order.

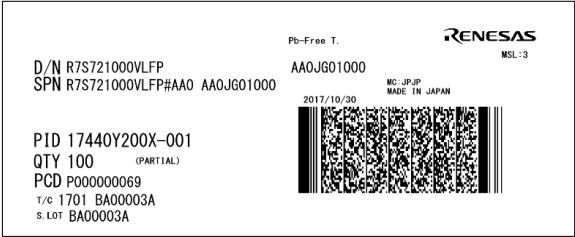
For additional information regarding this notice, please contact your Renesas sales representative.
--

Appendix

Label Specification

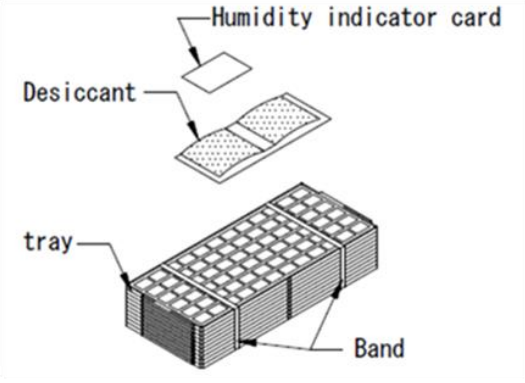
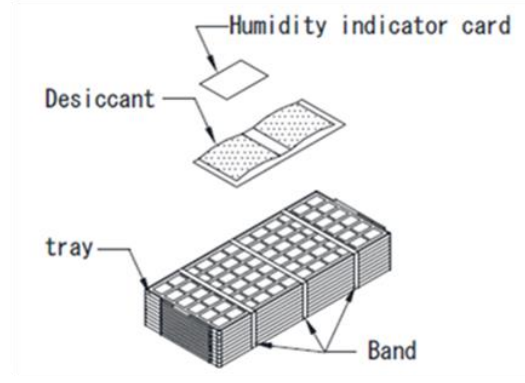
These are sample labels, and the areas highlighted in red indicate the changes.

If you can provide the T/C (trace code), Renesas can confirm traceability and provide the relevant information.

【Current】	【After Change】
 Current label details: - D/N R7S721000VLFP - SPN R7S721000VLFP#AA0 AA0JG01000 - Pb-Free T. - AA0JG01000 - RENESAS - MSL:3 2017/10/30 - MC:JP:JP - MADE IN JAPAN - PID 17440Y200X-001 - QTY 100 (PARTIAL) - PCD P000000069 - T/C 1701 BA00003A S. LOT BA00003A	 After Change label details: - D/N R7S721000VLFP - SPN R7S721000VLFP#AA1 AA1WM01000 - Pb-Free T. - AA1WM01000 - RENESAS - MSL:3 2017/10/30 - MC:TW:JP - ASSEMBLED IN JAPAN - FROM WAREHOUSE OF TAIWAN - PID 17440Y200Y-001 - QTY 100 (PARTIAL) - PCD P000006373 - T/C 1701 BA00004A S. LOT BA00004A The internal code will change. The country of manufacture label will be changed.

Packing Specification

The packing specification will be changed from two bands to three bands, as shown in the following figures.

【Current】 Final Test:Yonezawa	【After Change】 Final Test:Tera Probe
 Current packing diagram shows a tray of components with two bands. Labels include: Humidity indicator card, Desiccant, tray, and Band.	 After Change packing diagram shows a tray of components with three bands. Labels include: Humidity indicator card, Desiccant, tray, and Band.